

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chien-Wei Wang</td> <td>04/13/2009</td> </tr> <tr> <td>Ching-Yu Chang</td> <td>04/13/2009</td> </tr> </tbody> </table>		Name	Execution Date	Chien-Wei Wang	04/13/2009	Ching-Yu Chang	04/13/2009						
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CORRESPONDENCE DATA													
Fax Number: (214)200-0853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: (972) 739-8635 Email: Kim.Reyes@haynesboone.com Correspondent Name: Haynes and Boone, LLP Address Line 1: IP Section Address Line 2: 2323 Victory Avenue, Suite 700 Address Line 4: Dallas, TEXAS 75219													
ATTORNEY DOCKET NUMBER:	2008-0769 / 24061.1221												
NAME OF SUBMITTER:	Joseph R. Mencher												
Total Attachments: 2 source=240611221Assignment#page1.tif													

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PATENT
REEL: 022664 FRAME: 0196

Docket No.: 2008-0769 / 24061.1221
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|--|
| (1) | Chien-Wei Wang | of | No. 2, Alley 74, Lane 296, Minsheng Road
Wufong Township, Taichung County 413, Taiwan, R.O.C. |
| (2) | Ching-Yu Chang | of | No. 17, Hsinchen Road
Yuansun Village, Yilang County, Taiwan, R.O.C. |

have invented certain improvements in

METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE USING A MODIFIED PHOTSENSITIVE LAYER

for which we have executed an application for Letters Patent of the United States of America on May 11, 2009,
as U.S. Serial No. 12/463,501; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chien-Wei Wang

Residence Address: No. 2, Alley 74, Lane 296, Minsheng Road
Wufong Township, Taichung County 413, Taiwan, R.O.C.

Dated: 2009.4.13

Chien Wei Wang
Inventor Signature

Inventor Name: Ching-Yu Chang

Residence Address: No. 17, Hsinchen Road
Yuansun Village, Yilang County, Taiwan, R.O.C.

Dated: 2009.4.13

Ching-Yu Chang
Inventor Signature